	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definitio	Errors
1	BRS	48 77	laser with interconnect$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:52			0
2	BRS	39 5	second with laser with interconnect$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/01 19:40			0
3	BRS	1	second with laser with interconnect$6 and control$6 near collaps$6 near chip near connect$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 14:30			0
4	BRS	3	second with laser with interconnect$6 and (control$6 near collaps$6 near chip near connect$6 or c4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/01 19:39			0
5	BRS	15	second with laser with interconnect$6 and solder adj ball	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/01 19:41			0
6	BRS	18	second with laser with interconnect$6 and solder adj (ball or paste)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/01 19:49			0
7	BRS	2	second near laser with interconnect$6 and solder adj (ball or paste)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/01 19:50			0
8	BRS	19	second with energ$6 with laser with interconnect$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/01 19:52			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	ErrorDefinitio	Errors
9	BRS	176	laser with interconnect$6 with weld$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:13			0
10	BRS	108	laser with interconnect$6 and (control$6 near collaps$6 near chip near connect$6 or c4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 14:31			0
11	BRS	14	laser with interconnect$6 and (control$6 near collaps$6 near chip near connect$6 or c4) and weld$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 14:53			0
12	BRS	139	laser with weld$6 and (control$6 near collaps$6 near chip near connect$6 or c4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 15:00			0
13	BRS	97	laser near weld$6 and (control$6 near collaps$6 near chip near connect$6 or c4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 14:54			0
14	BRS	6	laser near weld$6 and (control$6 near collaps$6 near chip near connect$6 or c4) and solder adj ball and solder adj paste	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 14:55			0

	Typ e	Hi ts	Search Text	DBs	Time Stamp	Comments	Error Definitio	Errors
15	BRS	13	laser with weld$6 and (control$6 near collaps$6 near chip near connect$6 or c4) and solder adj ball and solder adj paste	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 15:23			0
16	BRS	33	4535219.URPN.	USPAT	2004/08/03 15:06			0
17	BRS	17	laser with (weld$6 or bond$6) and (control$6 near collaps$6 near chip near connect$6 or c4) and solder adj ball and solder adj paste	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 15:25			0
18	BRS	20 7	laser with (bond$6 or weld$6) and mcm	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:14			0
19	BRS	54	laser with (bond$6 or weld$6) and mcm and solder near ball	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:14			0
20	BRS	20	laser with (bond$6 or weld$6) and mcm and solder near ball and solder near paste	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:29			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Def Definitio	Errors
21	BRS	6	laser with (bond$6 or weld$6) and mcm and solder near ball and solder near paste and (c4 or control$6 near collaps$6 near chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:30			0
22	BRS	17	laser with (bond$6 or weld$6) and solder near ball and solder near paste and (c4 or control$6 near collaps$6 near chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:32			0
23	BRS	74	laser with (bond$6 or weld$6) and solder near ball and (c4 or control$6 near collaps$6 near chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:32			0
24	BRS	12	laser with (bond$6 or weld$6) and mcm and solder near ball and (c4 or control$6 near collaps$6 near chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:41			0

	Typ e	Hi ts	Search Text	DBs	Time Stamp	Comments	Error Definitio	Errors
25	BRS	12	laser with (reflow$6 or bond$6 or weld$6) and mcm and solder near ball and (c4 or control$6 near collaps$6 near chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:42			0
26	BRS	78	laser with (reflow$6 or bond$6 or weld$6) and solder near ball and (c4 or control$6 near collaps$6 near chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:42			0
27	BRS	22	laser with (reflow$6 or bond$6 or weld$6) and solder near ball and (c4 or control$6 near collaps$6 near chip) and paste	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:42			0
28	BRS	20	laser with (reflow$6 or bond$6 or weld$6) and solder near ball and (c4 or control$6 near collaps$6 near chip) and solder with paste	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:43			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	ErrorDefinitio	Errors
29	BRS	20	laser with (reflow$6 or bond$6 or weld$6) and solder with ball and (c4 or control$6 near collaps$6 near chip) and solder with paste	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:43			0
30	BRS	12 6	second with chip with bond$6 with laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 14:11			0
31	BRS	11	stack$6 near chip with bond$6 with laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 14:45			0
32	IS&R	2	("6133626").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 15:24			0
33	IS&R	2	("20040012938").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:08			0
34	IS&R	2	("6451626").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:54			0
35	BRS	14 7	bond$6 with (chip or die) with package with laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:55			0
36	BRS	20	bond$6 with (chip or die) with package with laser and solder adj ball	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 18:07			0
37	BRS	36 88	bond$6 with (chip or die) with package and solder adj ball	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:52			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	ErrorDefinitio	Errors
38	BRS	0	bond$6 with (chip or die) with intreposer with package and solder adj ball	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 18:07			0
39	BRS	12 6	bond$6 with (chip or die) with interposer with package and solder adj ball	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 18:08			0
40	BRS	3	bond$6 with (chip or die) with interposer with package and solder adj ball and laser with (heat$6 or reflow$6 or melt$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 18:09			0
41	BRS	58	bond$6 with (chip or die) with interposer with package and solder adj ball and laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 19:12			0
42	BRS	1	bond$6 with die with package with solder adj ball with lase	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 19:14			0
43	BRS	1	bond$6 with die with package with solder adj ball with lase	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 19:14			0
44	BRS	80	bond$6 same die with package with solder adj ball and laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 19:15			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	ErrorDefinitio	Errors
45	BRS	22	bond$6 with die with package with solder adj ball and laser with bond$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 19:15			0
46	BRS	0	bond$6 with (chip or die) with package and solder adj ball and "double data rate memory"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:53			0
47	BRS	14 0	"double data rate memory"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:53			0
48	BRS	33	"double data rate memory" and interconnect$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:54			0
49	BRS	3	"double data rate memory" and interconnect$6 and bond$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 21:37			0
50	BRS	2	"double data rate memory" and interconnect$6 and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 21:38			0